

Title of Change:	Marking change for WDFN6 part number LC05132C01NMTTTG		
Proposed first ship date:	20 June 2017 or earlier after customer approval		
Contact information:	Contact your local ON Semiconductor Sales Office or < Mutsuki.Niki@onsemi.com>		
Samples:	Contact your local ON Semiconductor Sales Office		
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <satoru.fujinuma@onsemi.com>.</satoru.fujinuma@onsemi.com>		
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>		
Change Part Identification:	Affected products will be identified with date code.		
Change category:	Wafer Fab Change Assembly Change Test Change Other: Marking		
Change Sub-Category(s): Manufacturing Site Change/Addition Manufacturing Process Change Product specific change		 □ Datasheet/Product Doc change □ Shipping/Packaging/Marking e □ Other: 	
Sites Affected: All site(s) not applicable ON Semiconductor site(s) : External Foundry/Subcon site(s) ON Carmona, Philippines			
 Description and Purpose: This Process Change Notification is to notify customers of the following change: Change marking design for WDFN6 to adopt the eject pin at mold release Change top mark from 3-liner to 2-liner 			
	Before Change	After Change	
	Description	Description	
Package design	No eject pin	Adopt the eject pin	
Marking design	05132 C01NT AYWW •	CD202 AYWW •	
Reliability Data Summary: N/A			
Electrical Characteristic Summary: Electrical characteristics are not impacted.			
List of affected Standard Parts:			
Part Number		Qualification Vehicle	
LC05132C01NMTTTG		NA	